



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): Wayne G. Renken
Title: Process Condition Sensing Wafer And Data Analysis System
Application No.: 10/685,550 Filing Date: October 14, 2003
Examiner: Charles D. Garber Group Art Unit: 2856
Docket No.: SENS.005US1 Conf. No.: 4924

Certificate of Mailing Under 37 CFR 1.8

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on June 22, 2004

Signature

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

INFORMATION DISCLOSURE STATEMENT

Dear Sir:

Pursuant to 37 C.F.R. §§ 1.56, 1.97 and 1.98, Applicant(s) call(s) the documents listed on the enclosed Form PTO-1449 to the Examiner's attention in this patent application..

This application has a filing date after June 30, 2003. Copies of the U.S. Patent(s) and U.S. Published Patent Application(s) documents listed on the accompanying Form PTO-1449 are not enclosed.

Citation of these documents shall not be construed as (1) an admission that the documents are prior art with respect to the invention or inventions claimed in this application, (2) a representation that a search has been made (other than as indicated by any cited

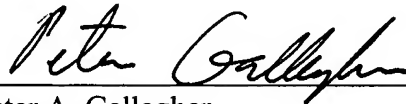
Attorney Docket No.:
SENS.005US1

Application No.:
10/685,550

document), or (3) an admission that the cited information is, or is considered to be, material to patentability as defined in § 1.56(b).

This information disclosure statement is submitted under 37 C.F.R. § 1.97(b) and consequently no fee should be required. The Commissioner is authorized, however, to charge any fee that may be required, or to credit any overpayment, against Deposit Account No. 502664. This form is being submitted in duplicate.

Respectfully submitted,



Peter A. Gallagher
Reg. No. 47,584

June 22, 2004

Date

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| U.S. Department of Commerce, Patent and Trademark | | Atty. Docket No. | Application No. |
| INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use several sheets if necessary) | | SENS.005US1 | 10/685,550 |
| | | Applicant(s) | Conf. No. |
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| Examiner | | | Date Considered | | | | | |
| *EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with your communication to applicant. | | | | | | | | |